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17. (ONCE AMENDED) A process of manufacturing a plurality of fluid jetting apparatuses at once, comprising:

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forming a nozzle part on a silicon wafer by a spinning process;
adhering the nozzle part with the silicon wafer to a membrane;
removing the silicon wafer from the nozzle part; and
adhering the membrane to a heat driving part to form the fluid jetting apparatuses.

21. (ONCE AMENDED) A process of manufacturing a plurality of fluid jetting apparatuses at once, comprising:

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forming a nozzle part on silicon wafer by a spinning process, the forming the nozzle part comprising:

forming jetting fluid barriers on the nozzle plate by the spinning process;
forming a first reinforcing element on the first substrate;
forming jetting fluid chambers in the jetting fluid barriers; and
forming nozzles in the nozzle plate;

forming a membrane, the forming the membrane comprising

forming a polyimide coating layer on a second substrate of silicon wafer;
forming an adhesive polyimide coating layer on the polyimide coating layer;
forming a second reinforcing element on the adhesive polyimide coating layer;

and

separating the polyimide coating layer from the second substrate after forming the second reinforcing element on the adhesive polyimide coating layer;
adhering the nozzle part with the silicon wafer to the membrane;
removing the silicon wafer from the nozzle part; and
adhering the membrane to a heat driving part.

27. (ONCE AMENDED) A process of manufacturing a plurality of fluid jetting apparatuses, comprising:

forming a nozzle part on a first substrate of silicon wafer by a spinning process;
forming a membrane on a second substrate of silicon wafer by the spinning process;
forming a heat driving part by forming electrodes and heat elements on a third substrate of silicon wafer; and
adhering the nozzle part to the membrane, and the membrane to the heat driving part to form the fluid jetting apparatuses.

37. (NEW) The process of claim 1, wherein said forming the nozzle part comprises:
spinning a raw material on a substrate to form the nozzle part; and
forming nozzles in the nozzle part such that each fluid jetting apparatus includes a formed nozzle.

38. (NEW) The process of claim 1, further comprising splitting the fluid jetting apparatus in the form of the wafer into separate fluid jetting apparatuses.

39. (NEW) The process of claim 17, wherein said forming the nozzle part comprises:
spinning a raw material on the silicon wafer to form the nozzle part; and
forming nozzles in the nozzle part such that each fluid jetting apparatus includes a formed nozzle.

40. (NEW) The process of claim 17, further comprising splitting the adhered nozzle part, membrane, and heat driving part into separate fluid jetting apparatuses.

41 (NEW) The process of claim 27, wherein said forming the nozzle part comprises:
spinning a raw material on the first substrate of the silicon wafer to form the nozzle part;
and
forming nozzles in the nozzle part such that each fluid jetting apparatus includes a formed nozzle.

42. (NEW) The process of claim 27, further comprising splitting the adhered nozzle part, membrane, and heat driving part into separate fluid jetting apparatuses.

43. (NEW) The process of claim 31, further comprising forming the nozzle part, said forming the nozzle part comprising:

forming the nozzle part on a substrate; and

forming nozzles in the nozzle part such that each fluid jetting apparatus includes a formed nozzle.

44. (NEW) The process of claim 31, further comprising splitting the wafer type fluid jetting apparatus into separate fluid jetting apparatuses.

45. (NEW) A process of forming fluid jetting apparatuses, comprising:
adhering a nozzle part having nozzles to a membrane; and
adhering the membrane to a heat driving part to form fluid jetting apparatuses, each fluid jetting apparatus having one of the nozzles.

46. (NEW) The process of claim 45, further comprising
forming the nozzle part on a substrate; and
forming the nozzles in the formed nozzle part.

47. (NEW) The process of claim 45, further comprising splitting the adhered membrane, nozzle part, and heat driving part into separate fluid jetting apparatuses.